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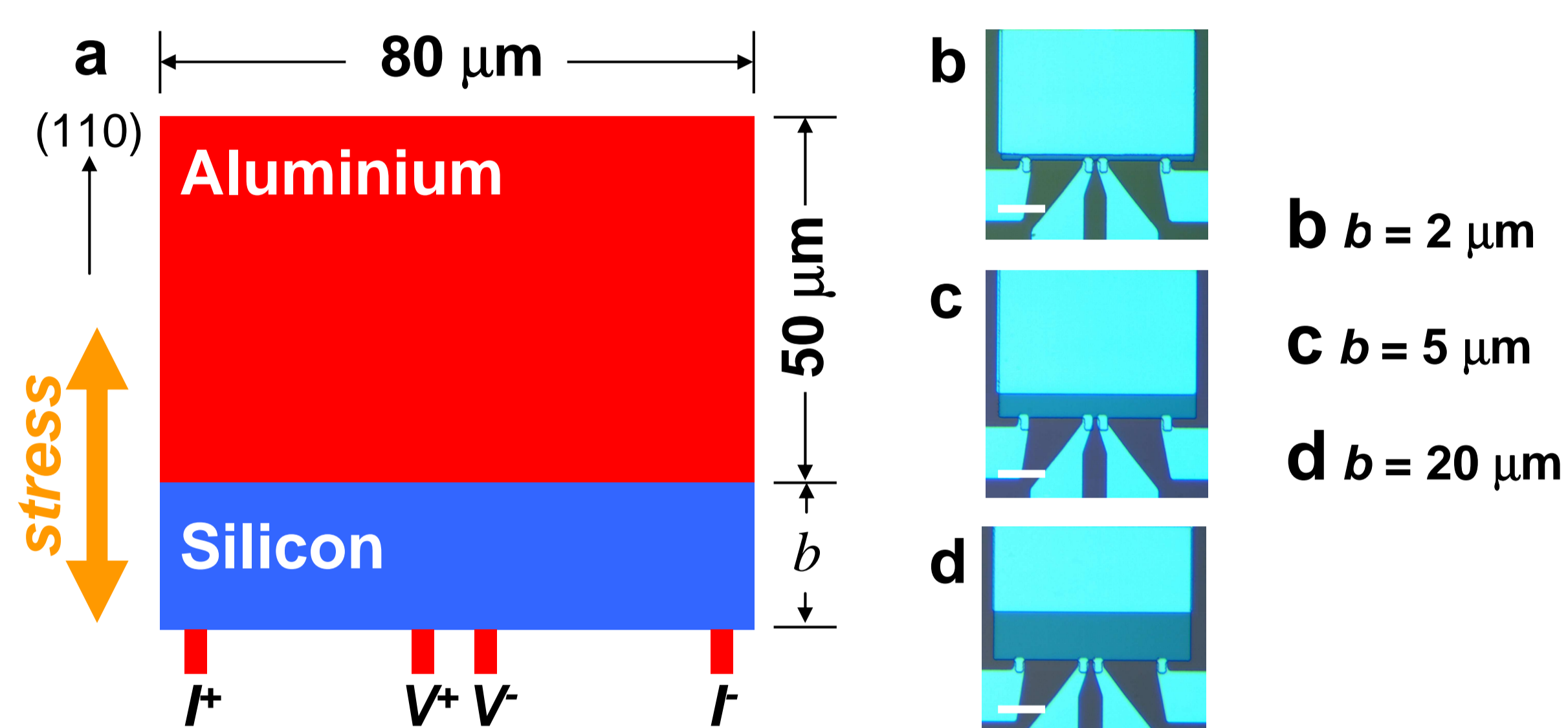
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**Goal:** study and understand the giant piezoresistance (i.e. change in resistance with applied mechanical stress) at semiconductor interfaces and surfaces. Apply these phenomenon to the detection of nano-scale strains in microsystems.

## Piezoresistive switch

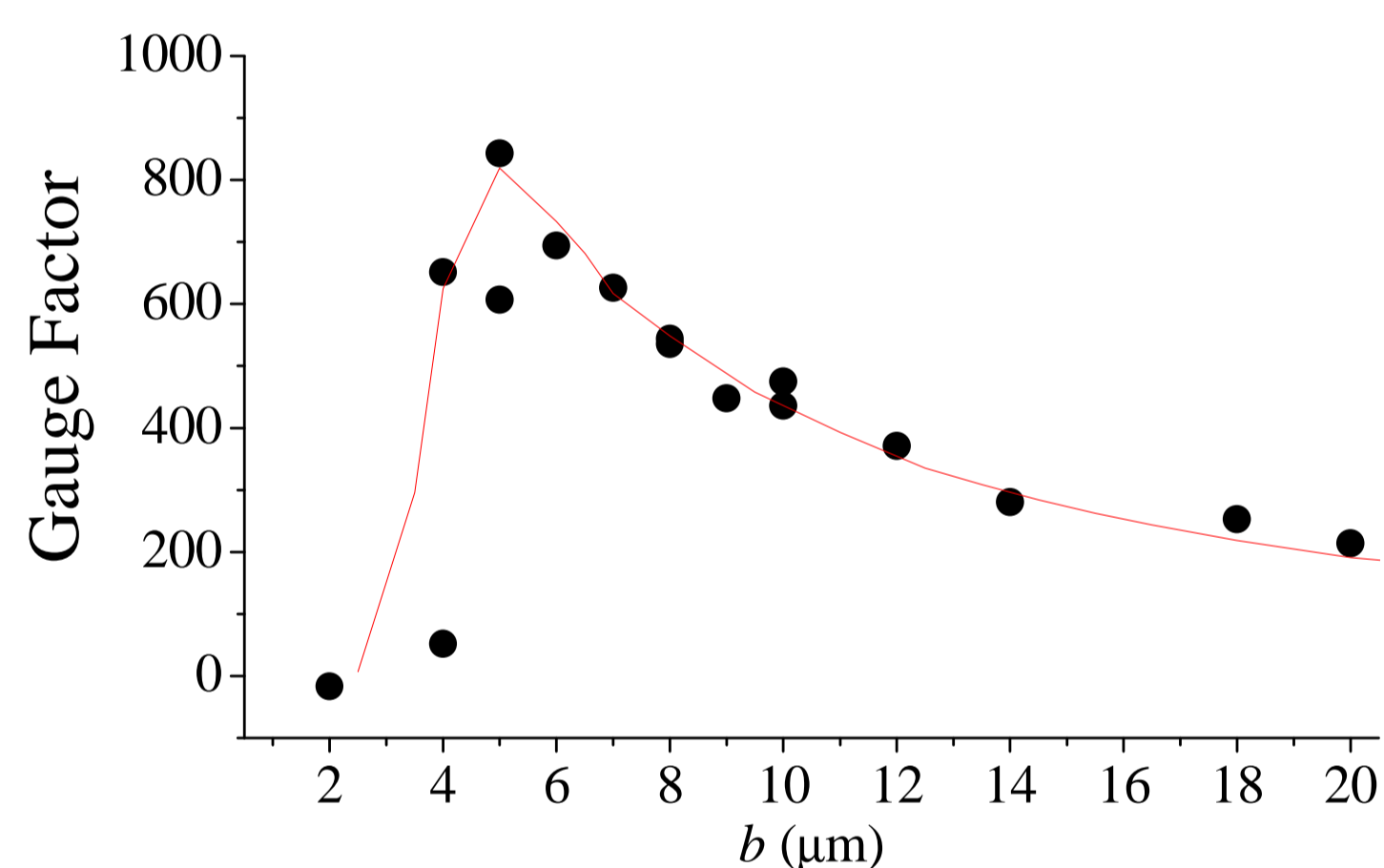
What is a metal-semiconductor hybrid?



What is the effect of a uni-axial tensile strain?

$$\sigma = \sigma_0 \begin{bmatrix} 1 - \frac{\chi}{2}(\pi_{11} + \pi_{12} - \pi_{44}) & 0 \\ 0 & 1 - \frac{\chi}{2}(\pi_{11} + \pi_{12} + \pi_{44}) \end{bmatrix}$$

for p-type silicon  
 $\pi_{11} = 6.6 \times 10^{-11} \text{ Pa}^{-1}$   
 $\pi_{12} = -1.1 \times 10^{-11} \text{ Pa}^{-1}$   
 $\pi_{44} = 138.1 \times 10^{-11} \text{ Pa}^{-1}$



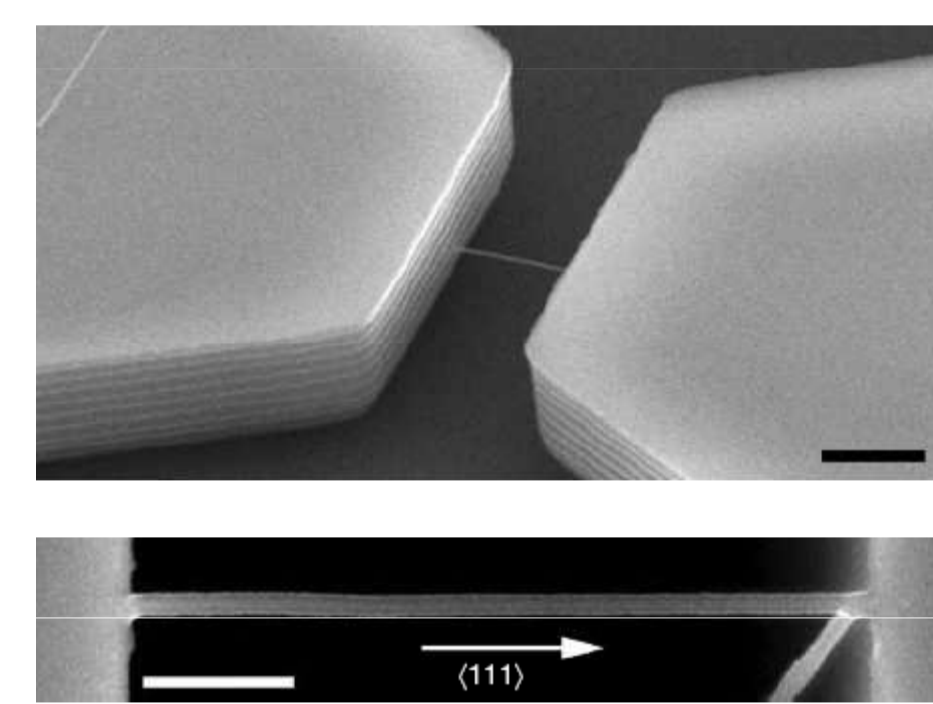
Physical Review Letters **100**, 145501 (2008)

➔ Towards a microsystem with integrated hybrid strain gauge.

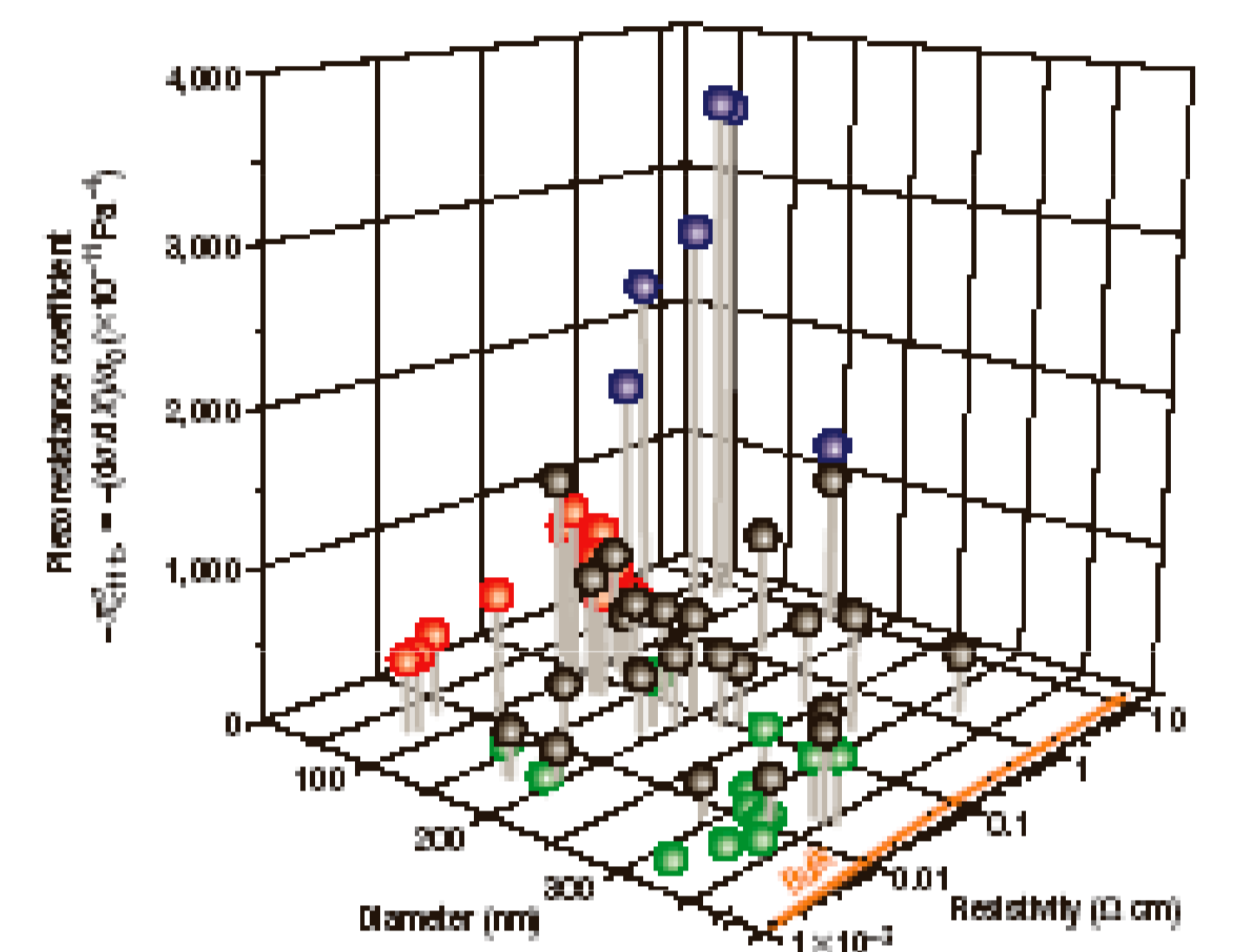
- confidential whitepaper study completed with a major player in the semiconductor industry.
- potential exploitation of the French Patent # 05 12740 , *Micro-electromechanical system with an integrated strain sensor*
- recruitment of a post-doctoral scientist to aid with prototype development.

## Piezopinich effect

Bottom up silicon nanowires.

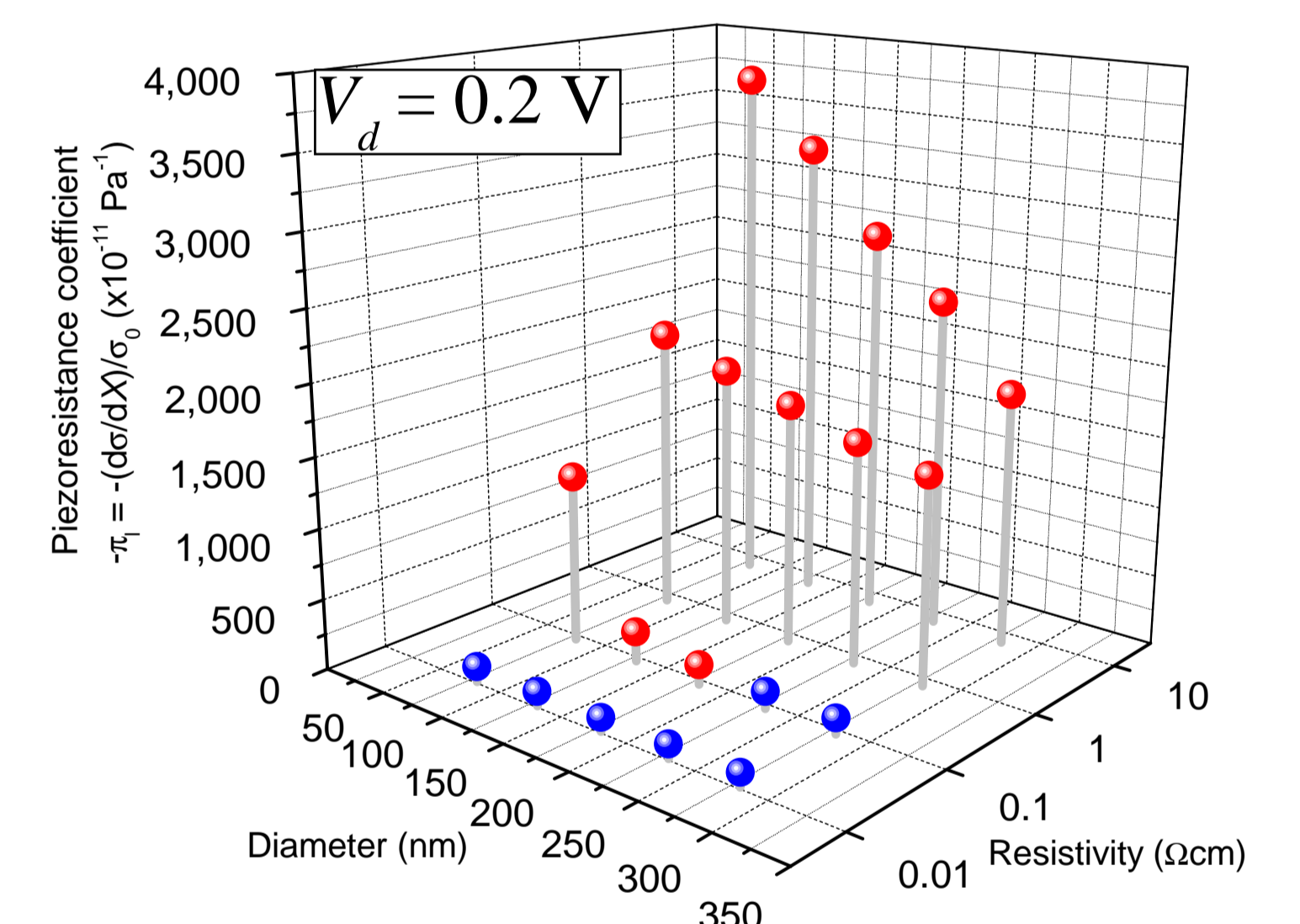
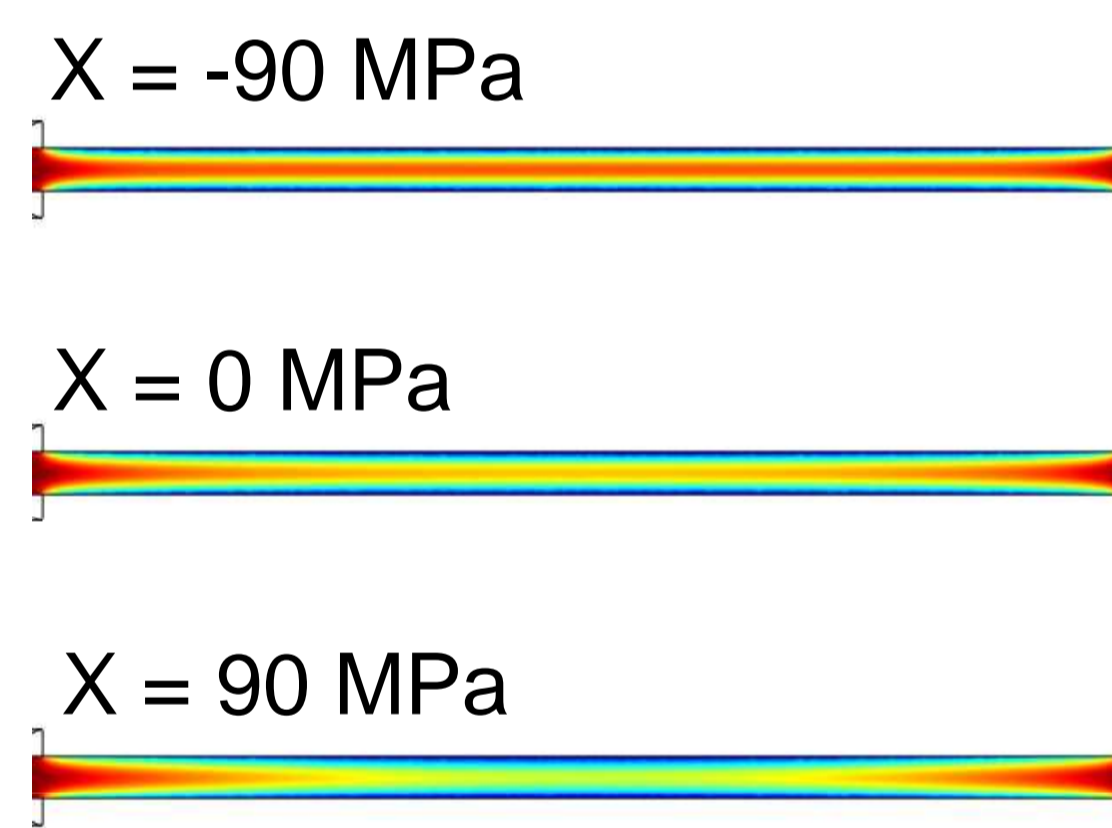


Diameter: 80 nm → 300 nm  
 Resistivity: 0.001 Ωcm → 10 Ωcm



From He & Yang, Nature Nanotech. 1, 42 (2006)

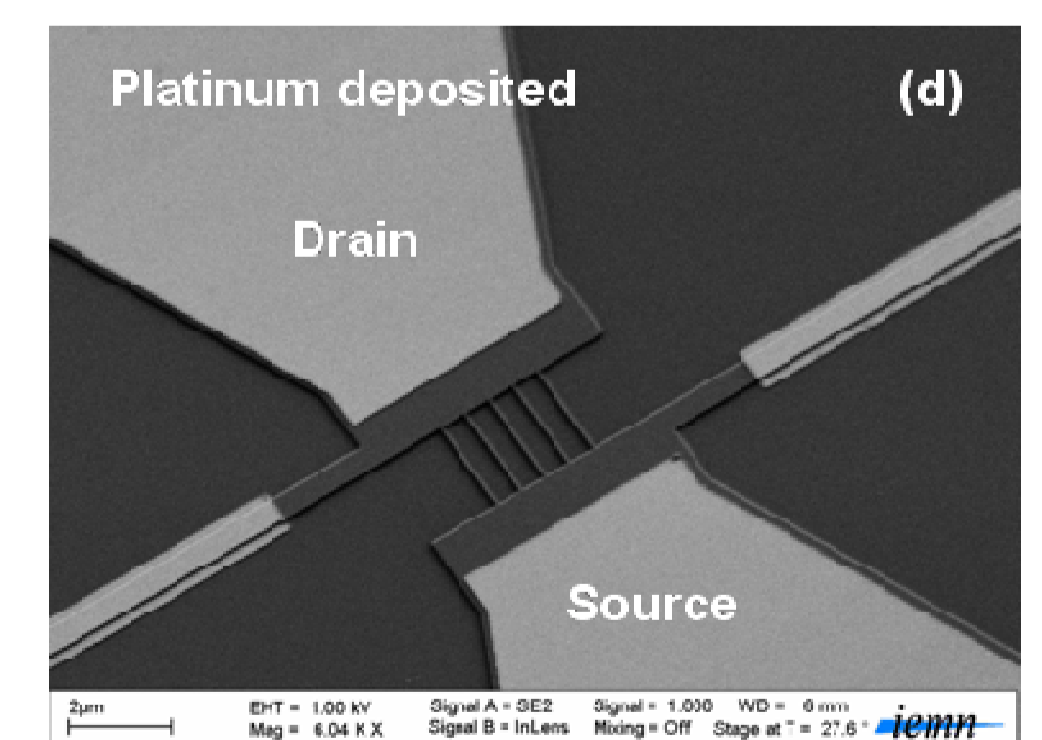
Surface depletion and stress: the piezo-pinch effect.



Nature Nanotechnology **3**, 311 (2008)

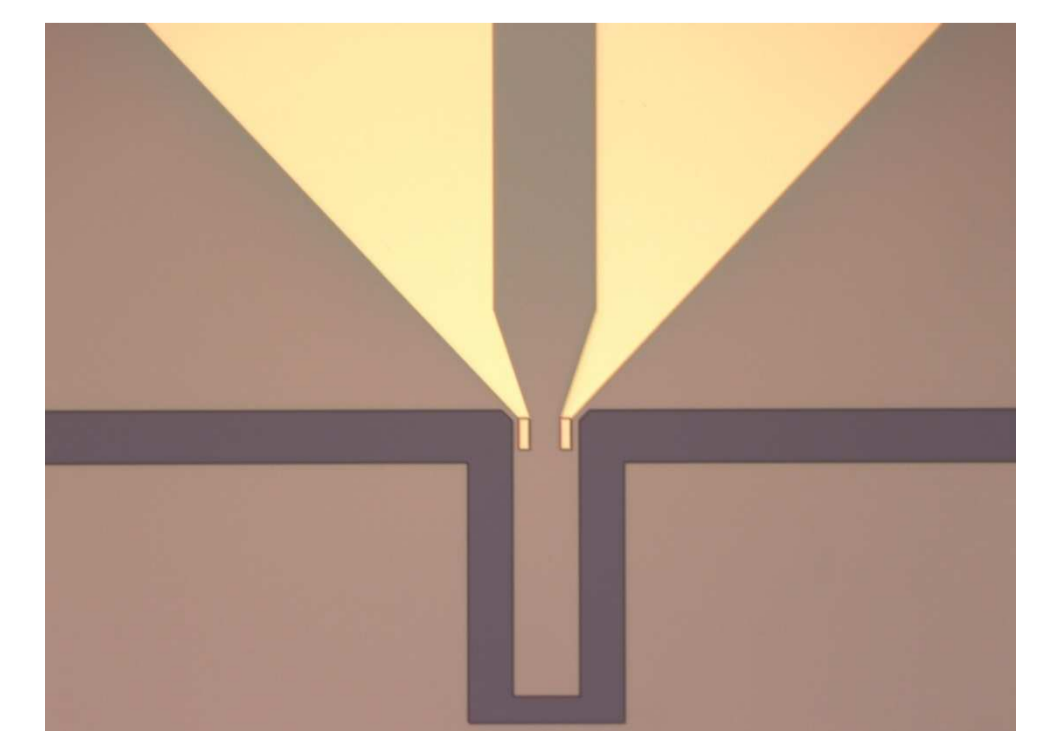
➔ Investigation of giant piezoresistance in depleted films and top-down fabricated nanowires.

- nanowire collaboration with J.P. Raskin (Université Catholique de Louvain, Belgique) and E. Dubois (IEMN)



Top down silicon nanowires fabricated at IEMN by V. Passi and S. Arscott

- on-cantilever integrated devices fabricated.



Piezopinich device integrated onto a silicon microcantilever